ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-	C, Bannockl	burn, Illinois. A	ll rights reserved nations.	under both	This docum level parts, t	ent is a declara	tion of the s encompasse	substances es all lowe	within the n er level mater	nanufacture rials for wh	er listed iter nich the mar	n. Note: nufacture	if the item is an as r has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Dis				 * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater 					ous Materia	ials and Mfg Information			
Supplier Information														
Company name*	Company uni	Company unique ID			Unique ID Authority					Response Date*				
nsemi											2025-06-07			
tact Name Title - Contact			et	Phone - C			Contact*			Email - Contact*				
roduct-Env-Stewards Product Envi			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representati			ntative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		umber Mfr Item Name			Effective Dat	e Version	.]	Manufacturing Site		W	eight*	UOM	Unit Type
	NVTFW G	VTFWS016N06CTA T6 60V SG Hig		her RDS-on portfolio		2025-06-07]	MY1		30	.365	mg	Each
Aanufacturing Proccess Informat	ion							·						
Terminal Plating / Grid Array Mat	erial 7	Ferminal Base A	Alloy	J-STD-020 MSL Ratir		Peak Pro	Process Body Temperature Ma		re Max Tin	ne at Peak 🛛	Temperature Number of Reflow Cycl		cles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		seconds	3			
omments														
vel 1 - maximum time at peak temperatur	e during so	Idering is 10-3	0 seconds											
or more information regarding material o	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.38	mg	Supplier	Zinc (Zn)	7440-66-6		0.0005	mg
			Supplier	Iron (Fe)	7439-89-6		0.0089	mg
			Supplier	Copper (Cu)	7440-50-8		0.3705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Solder	1.65	mg	Supplier	Silver (Ag)	7440-22-4		0.0413	mg
			А	Lead (Pb)	7439-92-1	7a	1.5263	mg
			Supplier	Tin (Sn)	7440-31-5		0.0825	mg
Lead Frame	12.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0074	mg
			Supplier	Iron (Fe)	7439-89-6		0.0124	mg
			Supplier	Copper (Cu)	7440-50-8		12.3864	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	15.0	mg		Epoxy resin	proprietary data		1.125	mg
			Supplier	Phenolic Resin	Proprietary Data		0.375	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.125	mg
			Supplier	Carbon Black (C)	1333-86-4		0.075	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3	mg
Plating	0.6	mg	Supplier	Tin (Sn)	7440-31-5		0.6	mg
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg